

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MT23-2500		SERIAL NO. 10799,794	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David L. Dickerson et al.			
				FILING DATE March 11, 2004		GROUP 3012	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
A.M	AA	6,100,160	0100	Hemets			
A.M	AB	6,010,947	0100	Kondo			
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes No
	AL						
	AM						
	AN						
	AO						
	AP						
OTHER REFERENCES (including Author, Title, Date, Periodic Pages, Etc.)							
A.M	AR		Welf, "Silicon Processing for the VLSI Era, Vol. 2: Process Integration," ©1990 Lattice Press, pages 51-56 (6 total pages).				
	AS						
	AT						
EXAMINER ANH D. MAI				DATE CONSIDERED 2/08/2005			
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Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MUT-2500		SERIAL NO. 10/779,794	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David L. Dickerson et al.			
				FILING DATE March 11, 2004		GROUP 2512	
U.S. PATENT DOCUMENTS							
Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate	
A-M	AA	3,801,932	09/91	Yasag			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
Document Number	Date	Country	Class	Subclass	Translation		
					Yes	No	
	AL						
	AM						
	AN						
	AO						
	AP						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
AR		Walt "Kilburn Processing for the VLSI Era, Vol. 2: Process Integration" ©1990 Lattice Publ. pages 31-54 (6 total pages)					
EXAMINER		DATE CONSIDERED					
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LIST OF ART CITED BY APPLICANT (Use as many sheets as necessary)					APPLICANT David L. Dickerson et al.		
					FILING DATE Filed Herewith		GROUP Unknown
U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
A.M.	AA	5,674,775	10/7/97	Ho et al.			
	AB	6,040,232	3/21/00	Gao			
	AC	6,074,932	6/13/00	Wu			
	AD	6,090,684	7/18/00	Ishitsuka et al.			
	AE	6,093,621	7/25/00	Tseng			
	AF	6,103,635	8/15/00	Chau et al.			
	AG	6,153,480	11/28/00	Arghavani et al.			
	AH	5,981,356	11/99	Hsueh et al.			
	AI	5,989,975	11/99	Kuo			
	AJ	6,153,478	11/00	Lin et al.			
	AK	6,232,203 B1	05/01	Huang			
	AL	6,249,035 B1	06/01	Peidous et al.			
FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
A.M.	AM	EP 0 782 185 A2	02.07.97	Europe (NEC Corporation)			
	AN	JP 11-67890		Japan			
	AO	JP 2000-269318	9/29/00	Japan			X
	AP						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)Q							
A.M.	AR	IBM Corp., <i>Optimized Shallow Trench Isolation Structure and Its Process for Eliminating Shallow Trench Isolation-Induced Parasitic Effects</i> .					
		34 IBM Technical Disclosure Bulletin, No. 11, pp. 276-277 (April 1992).					
	AR	Texas Instruments SPIE, Vol. 2875, <i>A Study of Integration Issues in Shallow Trench Isolation for Deep Submicron CMOS Technologies</i> ,					
		pgs. 39-43 Chatterje, Mason, Joyner, Rogers, Mercer, Kuchne, Esquivel, Mei, Montaza, Taylor, Ali, Nag, O'Brien, Ashburn and Chen					
	AS	S. Wolf et al, <i>Silicon Processing for the VLSI Era</i> , Vol. 1, page 366; 1986.					
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U.S. PATENT DOCUMENTS									
* Examiner Initial	Class	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
A-M	AA	4,663,832	05/12/87	Jarabotkar					
	AB	5,677,233	10/14/97	Abiko					
	AC	5,712,185	01/27/98	Tsai et al.					
	AD	5,780,346	07/14/98	Arghavani et al.					
	AE	5,801,083	09/01/98	Ye et al.					
	AF	5,895,254	04/20/99	Huang et al.					
	AG	5,397,733	3/14/95	Jang					
	AH	5,728,620	3/17/98	Park					
	AI	5,904,538	05/18/99	Son et al.					
	AJ	5,966,614	10/12/99	Park et al.					
	AK	6,083,808	7/4/00	Shin et al.					
	AL	5,863,827	01/26/99	Joyner					
FOREIGN PATENT DOCUMENTS									
		Document Number	Date	Country	Class	Subclass	Translation		
							Yes	No	
/	AM								
	AN								
	AO								
	AP								
	AQ								
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
A-M	AR		S. Wolf et al., Silicon Processing for the VLSI Era, Vol. 1, pages 522, 534, and 541; 1986.						
/	AS		K. Ishimaru et al., Trench Isolation Technology with 1 Micron Depth n-and p-Wells for a Full CMOS SRAM Cell with a 0.4 Micron. . . . IEEE 1994 pps. 97-98						
/	AT		Fazan & Mathews, "A Highly Manufacturable Trench Isolation Process for Deep Submicron DRAMs," IEEE 1993, 4 pages.						
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U.S. PATENT DOCUMENTS								
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A. M	AA	5,933,749	08/03/99	Lee				
	AB	5,937,308	08/10/99	Gardner et al.				
	AC	5,960,297	09/28/99	Saki				
	AD	5,356,828	10/18/94	Swan et al.				
	AE	5,976,948	11/02/99	Werner et al.				
	AF	5,962,342	10/05/99	Chuang et al.				
	AG	6,177,331 B1	01/23/01	Koga				
	AH	4,533,430	08/06/85	Bower				
	AI	4,882,291	11/21/89	Jeuch				
	AJ	5,258,332	11/02/93	Horioka et al.				
	AK	5,925,575	07/1999	Tao et al.				
	AL	5,904,523	05/1999	Feldman et al.				
	AM	5,374,585	12/1994	Smith et al.				
	AN	5,506,168	04/09/96	Morita et al.				
	AO	5,554,256	09/10/96	Pruijmboom et al.				
FOREIGN PATENT DOCUMENTS								
	Document Number	Date	Country	Class	Subclass	Translation		
						Yes	No	
	AP							
	AQ							
	AR							
	AS							
	AT							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AU							
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LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT David L. Dickerson et al.		
					FILING DATE Filed Herewith	GROUP Unknown	
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
A. M	AA	5,578,518	11/26/96	Koike et al.			
	AB	5,834,358	11/10/98	Pan et al.			
	AC	5,880,004	03/09/99	Ho			
	AD	6,245,640	06/12/01	Claussen et al.			
	AE	6,284,623 B1	09/04/01	Zhang et al.			
	AF	6,284,625 B1	09/04/01	Ishitsuka et al.			
	AG	6,287,921 B1	09/11/01	Chern			
	AH	6,121,113	09/19/00	Takatsuka et al.			
	AI	6,245,684	06/2001	Zhao et al.			
	AJ	5,843,846	12/1998	Nguyen et al.			
	AK	5,858,865	01/1999	Juengling et al.			
	AL	5,926,722	07/1999	Jang et al.			
	AM	6,274,498	08/2001	Moore et al.			
	AN	6,238,999	05/2001	Dickerson et al.			
	AO	4,534,826	08/1985	Goth et al.			
	AP	6,090,683	07/2000	Torek			
	AQ	5,817,566	10/1998	Jang et al.			
	AR	5,968,842	10/1999	Hsiao			
	AS	5,399,520	03/1995	Jang			
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation Yes No
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AT						
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